

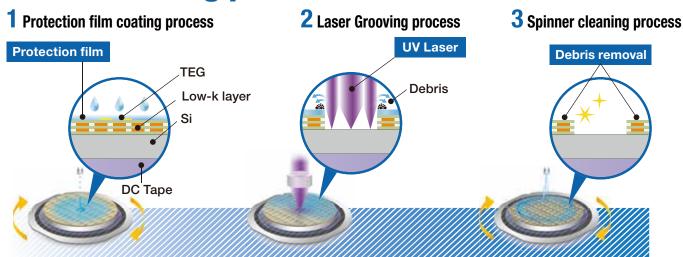
### **FULLY AUTOMATIC LASER GROOVING MACHINE**

# **AL3000**



- Ø300mm Compatible fully automatic laser dicing machine
   Automatically supports a series of processes from water-soluble protective film distribution to laser dicing and cleaning.
- Laser Grooving Process compatible
   AL3000 supports applications for removing TEG on low-k grooves or streets.
- Achieves both high quality processing and high throughput with a unique laser engine mechanism
- Enhanced ease of use
   Intuitive operation is possible using the LCD touch panel and simpler screen configuration and iconization by GUI (Graphical User Interface).

# **Laser Grooving process**



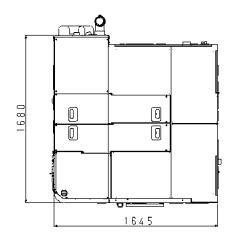
## **Specifications**

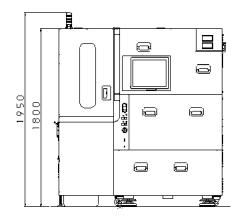
Model Name		AL3000
Processing method		Ablation
Laser oscillator		Semiconductor Laser excitation Q-Swith Solid-State Laser
Wavelength(nm)		355
Max. workpeice size(mm)		Ф305
Cutting stroke (mm)		310 x 310
X-axis	Max. Mooving speed(mm/sec)	1,000
Y-axis	Max. Mooving speed(mm/sec)	300
	Positioning accuracy (µm)	0.078
Z-axis	Max. Mooving speed(mm/sec)	10
	Repeatability accuracy (µm)	1.0
θ-axis	Max. rotaing angle(deg)	380.0

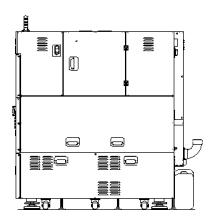
Power supply(V)	3-phase 200 $\sim$ 220VAC±10% 50/60Hz (380, and 415 V are available with optional transformer)		
Power consumption(kVA)	2.0 (Reference values)		
Air supply pressure(MPa)	$0.5 \sim 0.7$		
Average air consumption(L/min)	400		
N2 supply pressure(MPa)	$0.3 \sim 0.5$		
N2 average consumption(L/min)	30		
DI water supply pressure(MPa)	$0.3 \sim 0.5$		
Maximum DI water consumption flow rate(L/min)	6.0		
Exhaust (m3/min)	4.0 or more		
Dimensions WxDxH (mm)	1,645 x 1,680 x 1,800		
Machine weight (kg)	2,500		

<sup>\*</sup>In addition to the above, a chiller unit and dust collector are included as ancillary equipment.

#### **External View**







## **ACCRETECH**

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